

IIDAP14.001AUS

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant	:	USAMI et al.)	Group Art Unit 1742
)	
Appl. No.	:	09/966,389)	
)	
Filed	:	September 27, 2001)	
)	
For	:	HIGH MECHANICAL)	
		STRENGTH COPPER ALLOY)	
)	
Examiner	:	Sikyin Ip		

OFFICE ACTION RESPONSE

United States Patent and Trademark Office
P.O. Box 2327
Arlington, VA 22202

Dear Sir:

In response to the Office Action dated December 12, 2001, please amend the above captioned patent application as set forth below.

IN THE CLAIMS:

1. (Amended) A high-mechanical strength copper alloy, consisting essentially of 3.5 to 4.5% by mass of Ni, 0.7 to 1.0% by mass of Si, 0.01 to 0.20% by mass of Mg, 0.05 to 1.5% by mass of Sn, 0.2 to 1.5% by mass of Zn, and less than 0.005% by mass (including 0% by mass) of S, with the balance being made of Cu and inevitable impurities,

wherein a diameter of a crystal grain in the alloy is from more than 0.001 mm to 0.025 mm; and the ratio (a/b), between a longer diameter a of a crystal grain on a cross section parallel to a direction of final plastic working, and a longer diameter b of a crystal grain on a cross section perpendicular to the direction of final plastic working, is 1.5 or less, and